

BAS16DXV6T1, BAS16DXV6T5

Preferred Device

Dual Switching Diode

Features

- Pb-Free Packages are Available

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Continuous Reverse Voltage	V _R	75	V
Recurrent Peak Forward Current	I _F	200	mA
Peak Forward Surge Current Pulse Width = 10 μs	I _{FM(surge)}	500	mA

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C	P _D	357 (Note 1)	mW
Derate above 25°C		2.9 (Note 1)	mW/°C
Thermal Resistance Junction-to-Ambient	R _{θJA}	350 (Note 1)	°C/W
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C	P _D	500 (Note 1)	mW
Derate above 25°C		4.0 (Note 1)	mW/°C
Thermal Resistance Junction-to-Ambient	R _{θJA}	250 (Note 1)	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

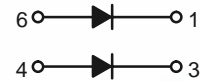
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 @ Minimum Pad



ON Semiconductor®

<http://onsemi.com>



SOT-563
CASE 463A
PLASTIC

MARKING DIAGRAM



A6 = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
BAS16DXV6T1	SOT-563	4 mm pitch 4000/Tape & Reel
BAS16DXV6T1G	SOT-563 (Pb-Free)	4 mm pitch 4000/Tape & Reel
BAS16DXV6T5	SOT-563	2 mm pitch 8000/Tape & Reel
BAS16DXV6T5G	SOT-563 (Pb-Free)	2 mm pitch 8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.



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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
Forward Voltage ($I_F = 1.0\text{ mA}$) ($I_F = 10\text{ mA}$) ($I_F = 50\text{ mA}$) ($I_F = 150\text{ mA}$)	V_F	– – – –	715 855 1000 1250	mV
Reverse Current ($V_R = 75\text{ V}$) ($V_R = 75\text{ V}, T_J = 150^\circ\text{C}$) ($V_R = 25\text{ V}, T_J = 150^\circ\text{C}$)	I_R	– – –	1.0 50 30	μA
Capacitance ($V_R = 0, f = 1.0\text{ MHz}$)	C_D	–	2.0	pF
Reverse Recovery Time ($I_F = I_R = 10\text{ mA}, R_L = 50\ \Omega$) (Figure 1)	t_{rr}	–	6.0	ns
Stored Charge ($I_F = 10\text{ mA}$ to $V_R = 6.0\text{ V}, R_L = 500\ \Omega$) (Figure 2)	QS	–	45	PC
Forward Recovery Voltage ($I_F = 10\text{ mA}, t_r = 20\text{ ns}$) (Figure 3)	V_{FR}	–	1.75	V

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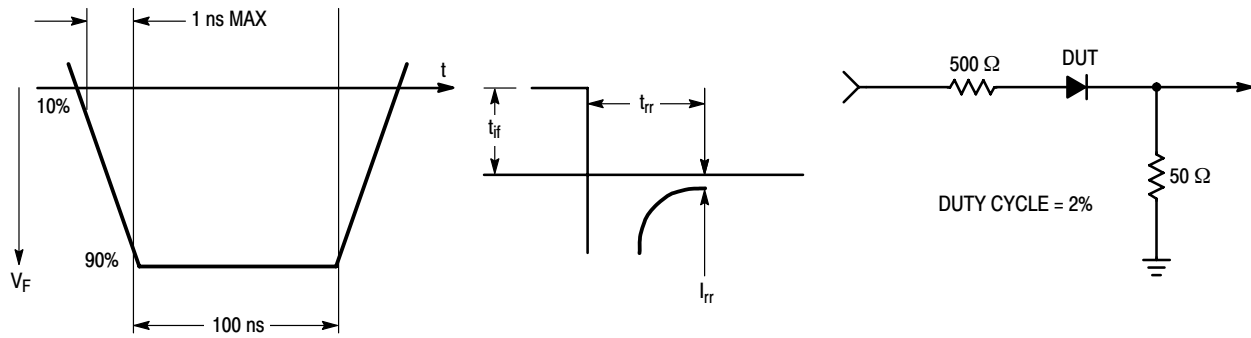


Figure 1. Reverse Recovery Time Equivalent Test Circuit

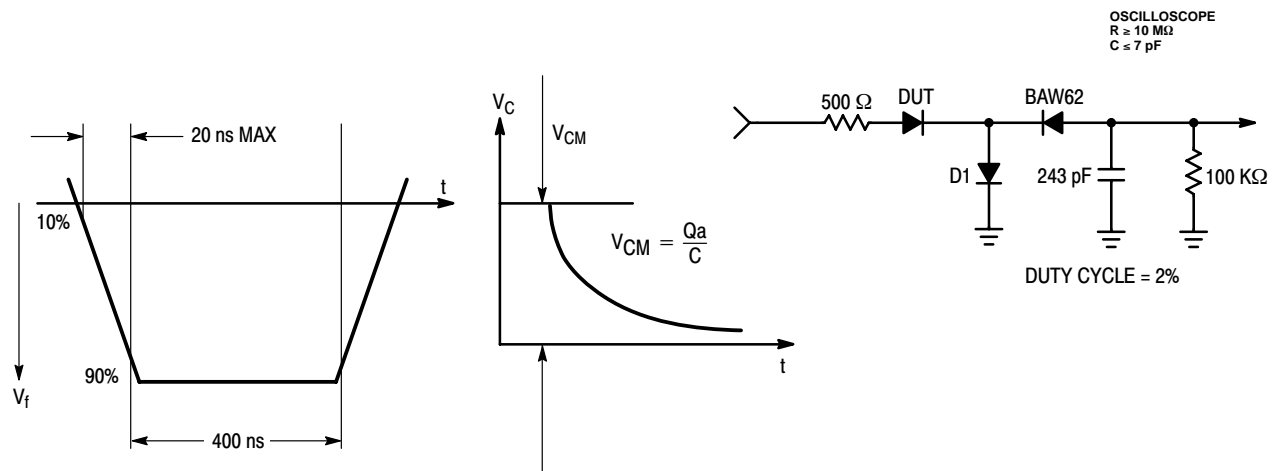


Figure 2. Stored Charge Equivalent Test Circuit

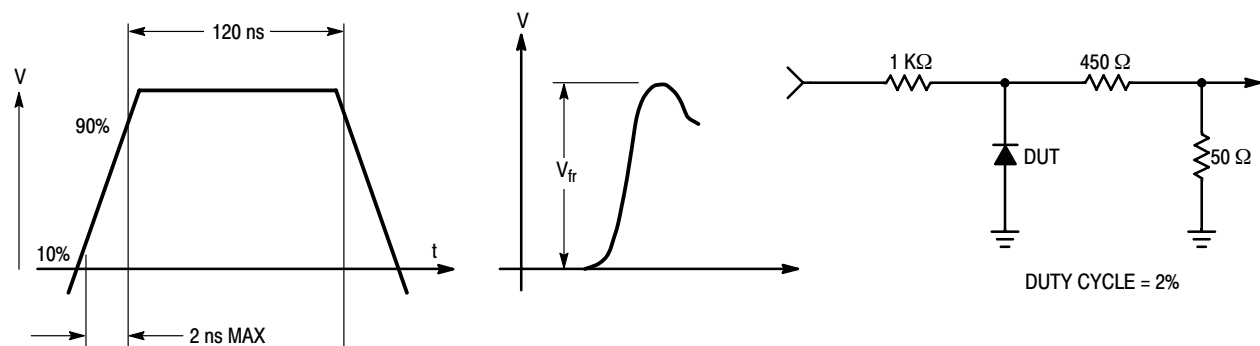


Figure 3. Forward Recovery Voltage Equivalent Test Circuit

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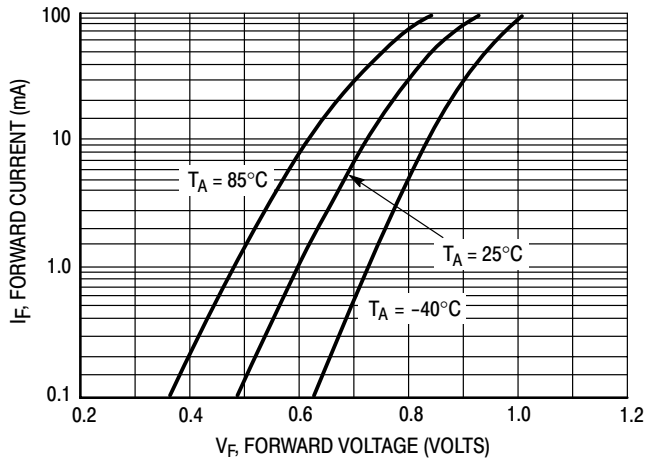


Figure 4. Forward Voltage

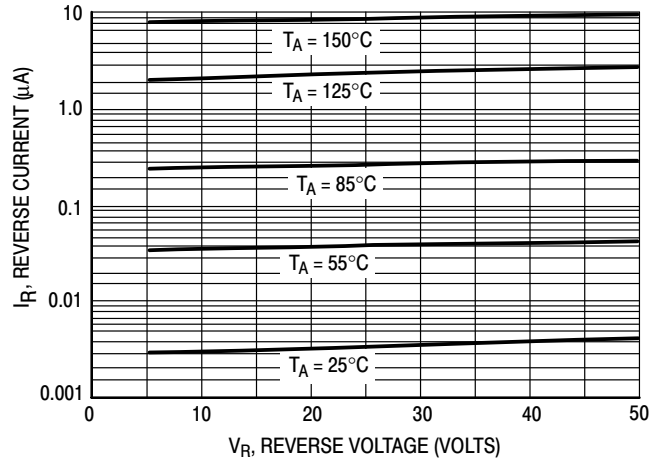


Figure 5. Leakage Current

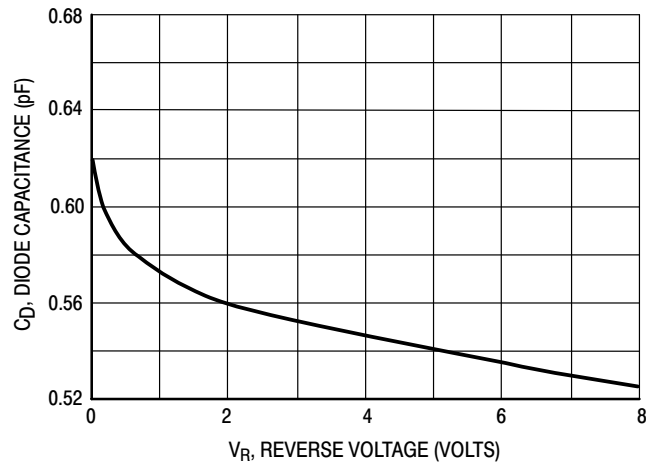


Figure 6. Capacitance

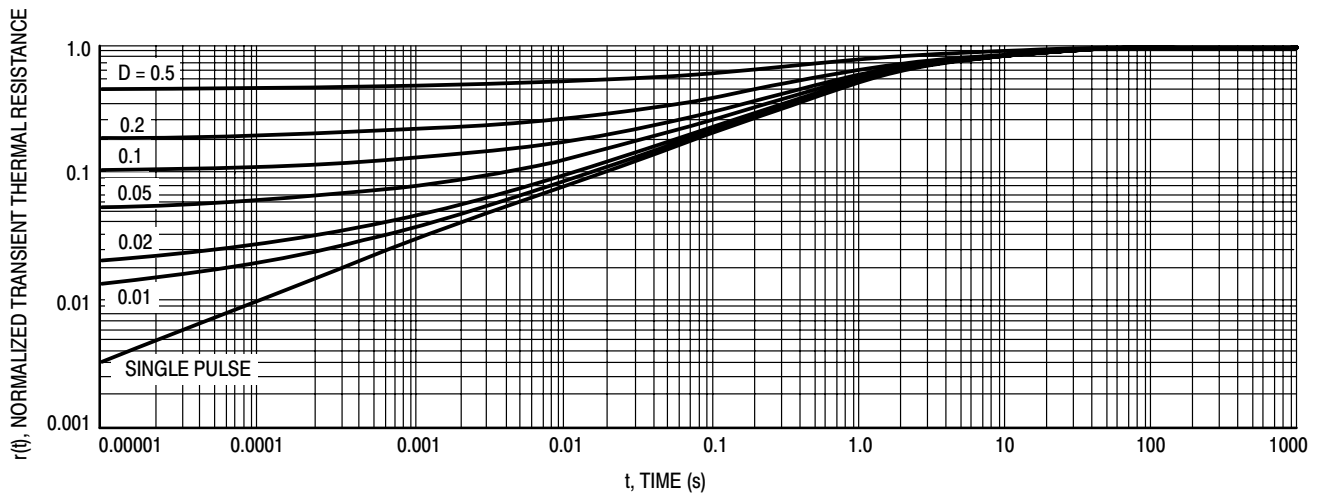
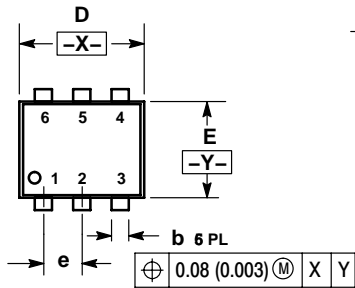


Figure 7. Normalized Thermal Response

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PACKAGE DIMENSIONS

SOT-563, 6 LEAD
CASE 463A-01
ISSUE F



NOTES:

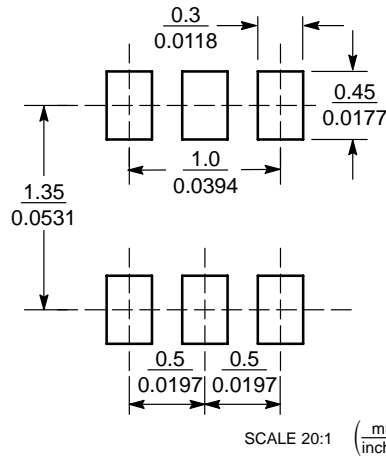
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.50	0.55	0.60	0.020	0.021	0.023
b	0.17	0.22	0.27	0.007	0.009	0.011
C	0.08	0.12	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.062	0.066
E	1.10	1.20	1.30	0.043	0.047	0.051
e	0.5 BSC			0.02 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012
H _E	1.50	1.60	1.70	0.059	0.062	0.066

STYLE 10:


- PIN 1. CATHODE 1
- N/C
- CATHODE 2
- ANODE 2
- N/C
- ANODE 1

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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